Abstract

Method for the Double Sided Polishing of a Semiconductor Wafer

The invention relates to a method for the double sided polishing of a semiconductor wafer, comprising polishing a frontside of the semiconductor wafer in a first step by using a polishing pad with fixed abrasive, and simultaneously polishing a backside of the semiconductor wafer with a polishing pad that contains no abrasive, but during which a polishing agent containing abrasive is introduced between the polishing pad and the backside of the semiconductor wafer, subsequent inversion of the semiconductor wafer, and then in a second step polishing the backside of the semiconductor wafer with a polishing pad that contains fixed abrasive and simultaneously polishing the frontside of the semiconductor wafer with a polishing pad that contains no fixed abrasive, a polishing agent containing abrasive being introduced between the polishing pad and the frontside of the semiconductor wafer.

No Figure.